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(54) **METHOD FOR FORMING
FLIPPED-CONDUCTOR-PATCH**

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(57) **ABSTRACT**

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A method includes providing a layer of non-conductive material having a conductive electroplating seed layer formed on a surface thereof; applying a photoresist layer over the surface of the conductive electroplating seed layer; and defining wiring channels in the photoresist resist layer. The method includes electroplating a conductive material in the defined wiring channels; adhering a non-conductive layer over the photoresist layer and the plated conductive material in the wiring channels; and removing the layer of non-conductive material and the conductive electroplating seed layer.

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